

Test Results of TTF-V Couplers for ILC

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Context of the Input Power Coupler Activities @ LAL

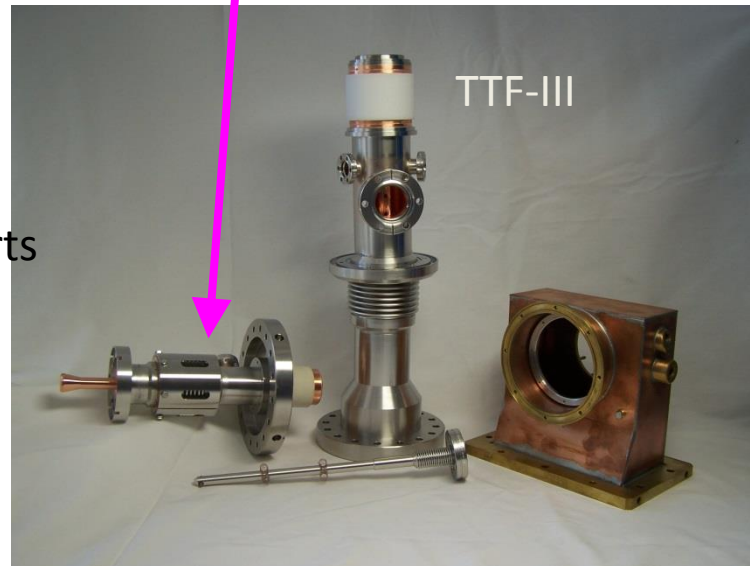
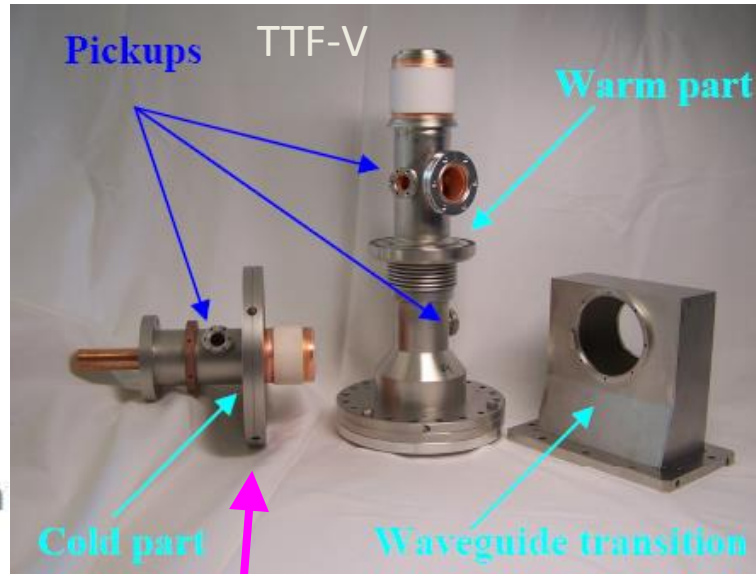
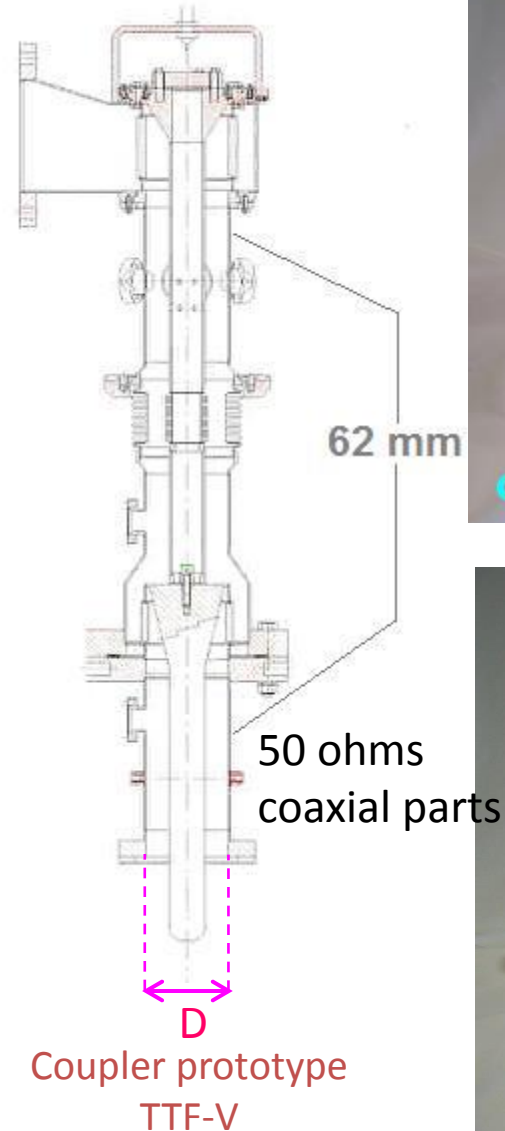
- ❑ Design and test of alternative Power Coupler Prototypes for ILC
- ❑ Close collaboration with DESY on Power Coupler R&D and XFEL Coupler Industrialization Studies
- ❑ The support of the European Community-Research Infrastructure Activity under the FP6 “Structuring the European Research Area” program (CARE).
- ❑ Collaboration with KEK on “R&D on High Power Couplers for the ILC» in the framework of the FJPPL

In this framework TTF-V couplers have been :

- **Designed:**
 - **Based on the TTF-III Coupler Design (Baseline ILC Power Coupler)**
 - **Design performed by Pierre LEPERCQ (LAL)**
- **Then RF power tested**

TTF-V Coupler Prototype

Pierre Lepercq RF Studies
(LAL)



□ TTF-V is very similar to TTF-III, but, have larger cold part diameter in order to shift multipacting to higher power levels*.

□ TTF-V design have been simplified:

- No bellows in the cold part (fixed antenna penetration)
- Thermal design is not totally optimized

*Multipacting scaling law in coaxial lines:

$$P_{1\text{-point}} \sim (f \cdot D)^4 \cdot Z$$

$$P_{2\text{-point}} \sim (f \cdot D)^4 \cdot Z^2$$

Main Stages

- ❑ 2 pairs of TTF-V manufactured by ACCEL
- ❑ New test box designed (LAL) then manufactured by the same manufacturer
- ❑ All TTF-V Couplers cleaned using the TTF-III cleaning procedure.
- ❑ First Coupler pair RF Power tested @ LAL

The goal : RF conditioning using the TTF-III conditioning procedure (**1 MW for short pulses & 0.5 MW for 1.3 ms pulses**)

- ❑ Second Coupler pair RF Power tested @KEK

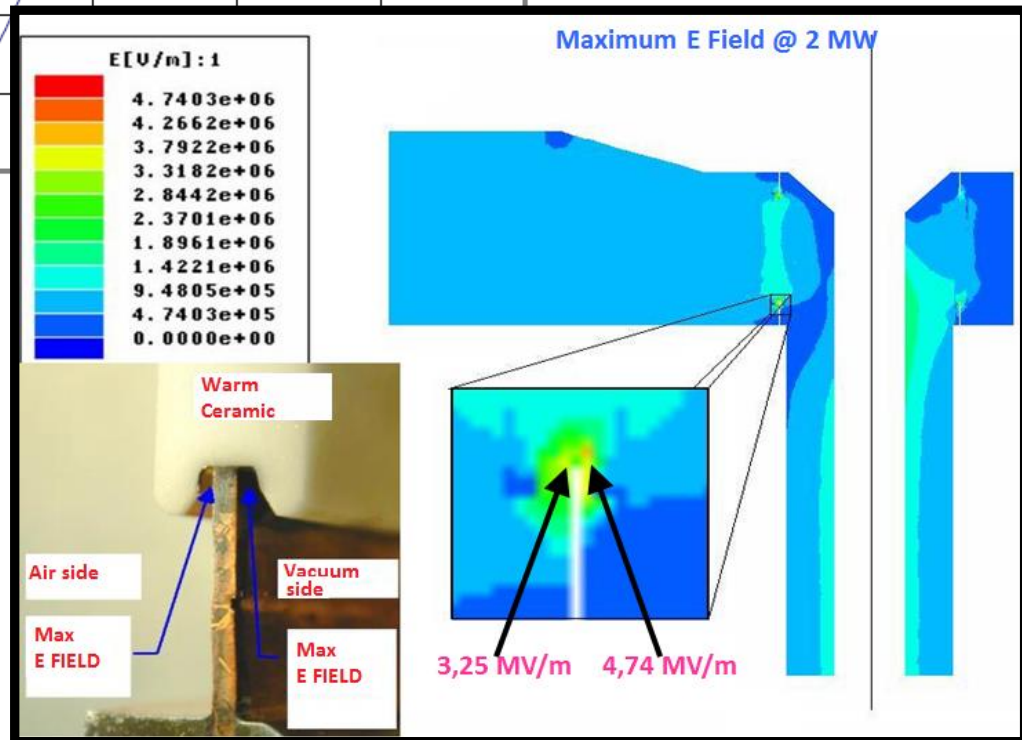
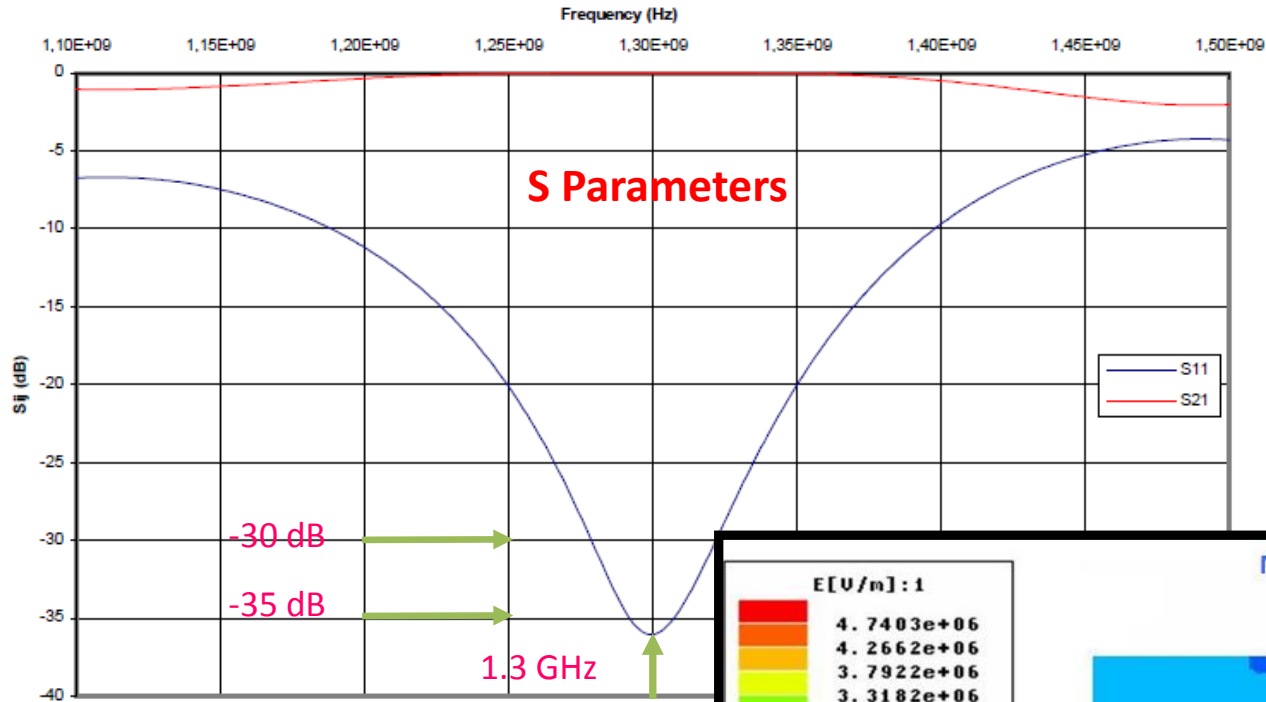
The goal:

- RF conditioning using the TTF-III conditioning procedure
- Then RF conditioning using ILC Power Couplers RF conditioning procedure @ KEK (**2 MW for short pulses & 1 MW for 1.5 ms pulses**)



TTF-V Power Coupler pair

RF Design

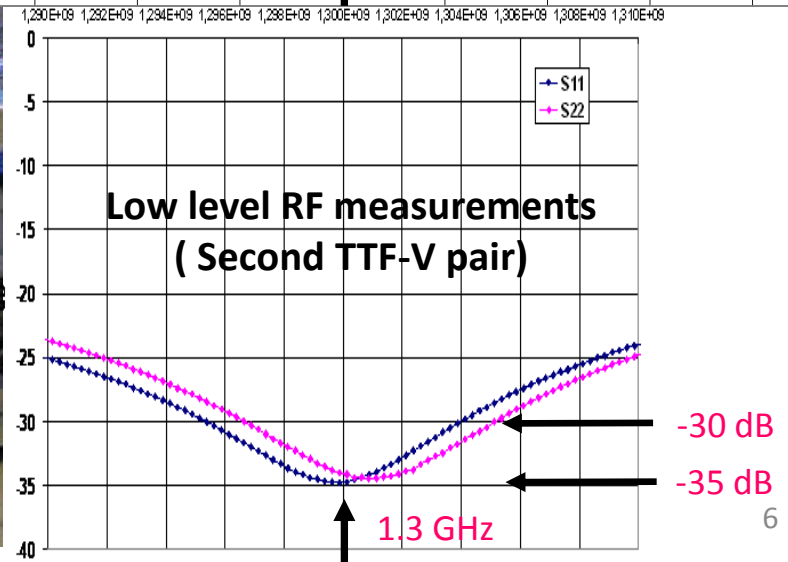
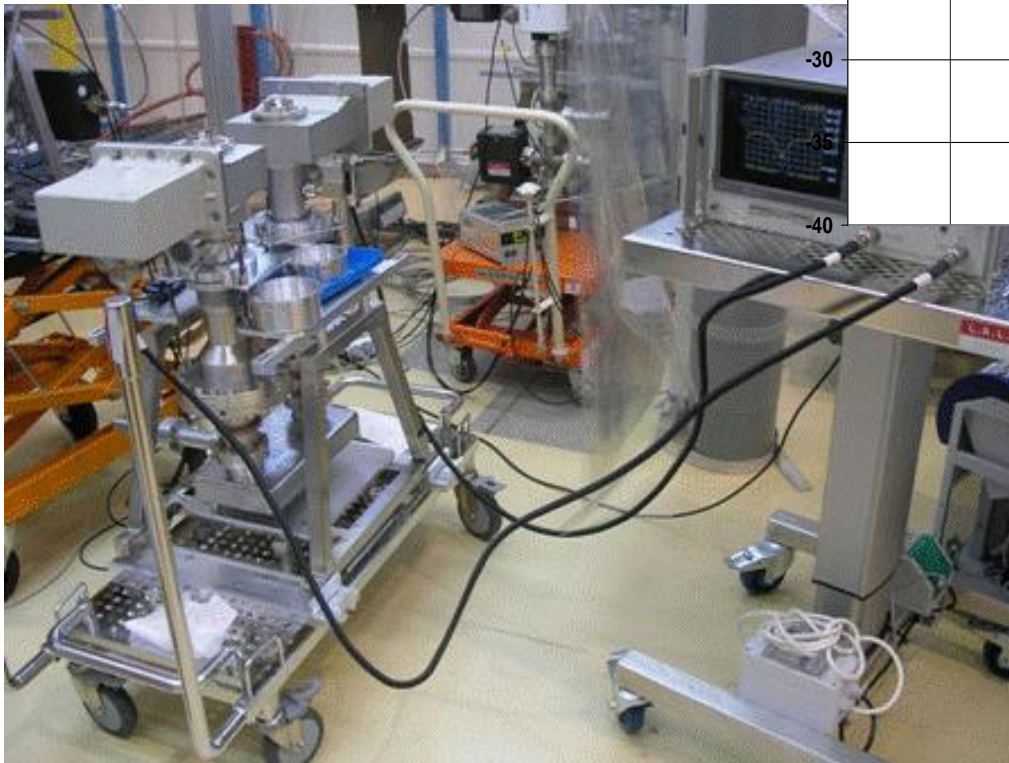
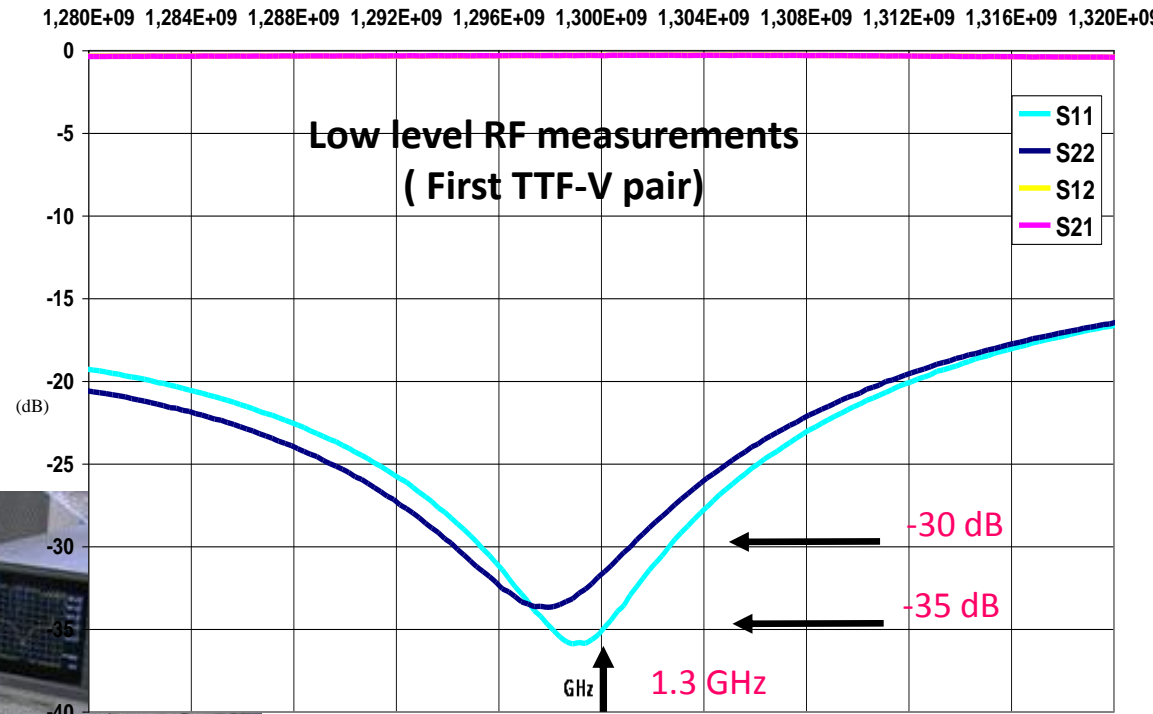


The maximum E field is located near the ceramic window

Low Level RF Measurements

Frequency (GHz)

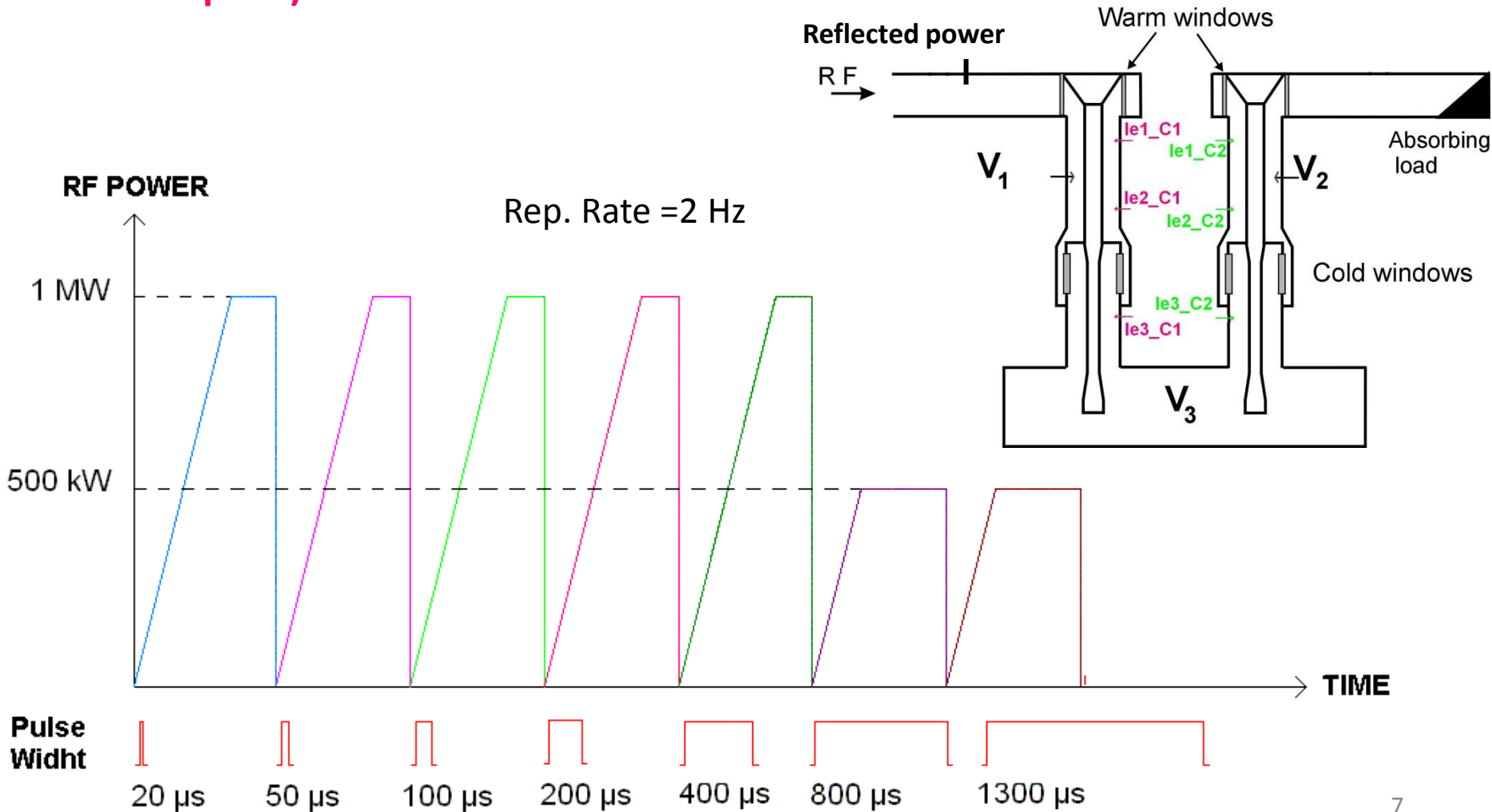
Good Low Level RF measurement results obtained for the two coupler pairs



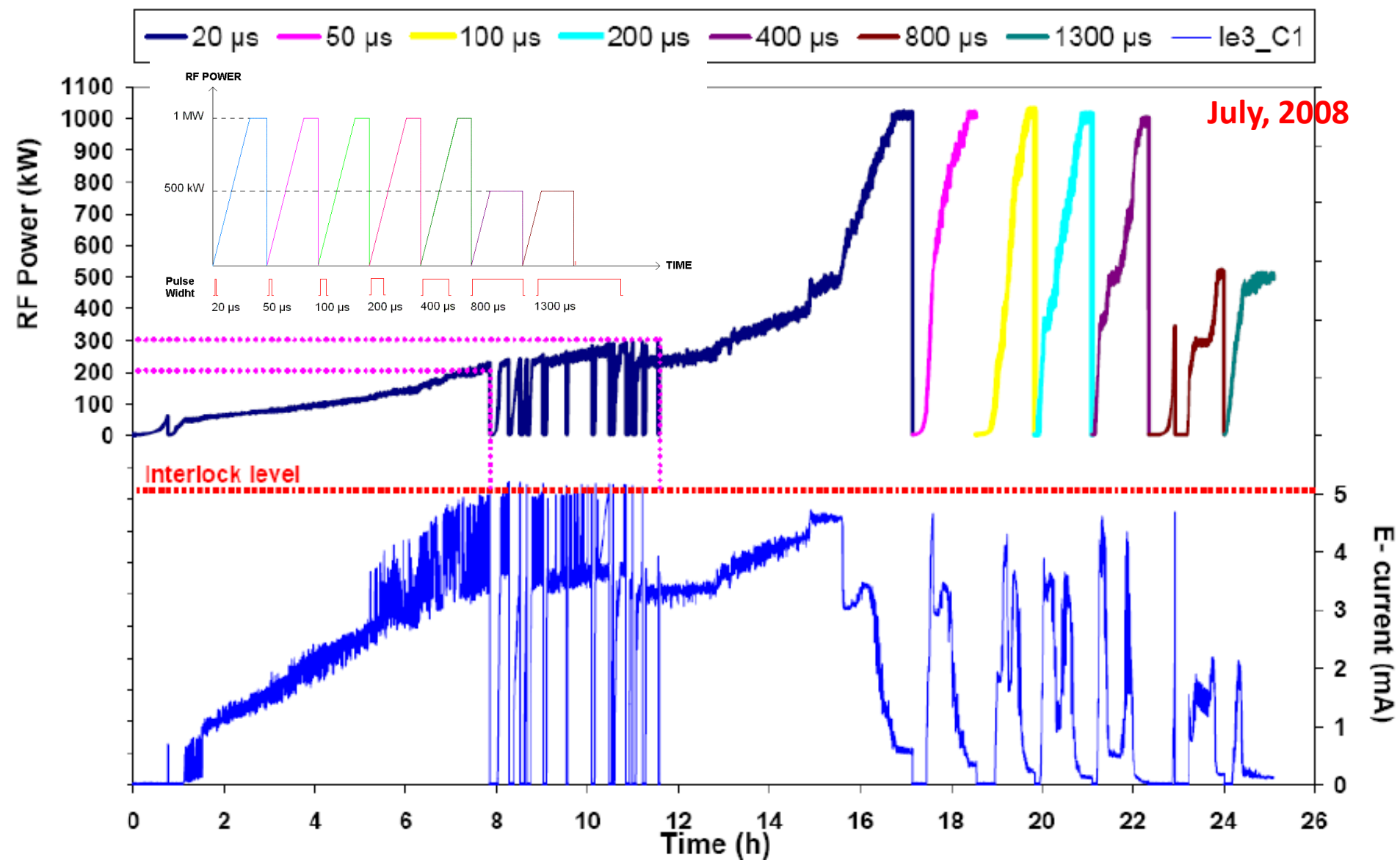
TTF-V RF Conditioning @ LAL (1)

Use of the TTF-III conditioning procedure:

Goal: To reach 1 MW for 400 μs pulses and 0.5 MW for 1300 μs pulses (as for TTF-III couplers).



TTF-V RF Conditioning @ LAL (2)



Easy conditioning in 24 h only

TTF-V RF Conditioning @ KEK (1)



January, 2009

Assembly in clean room ;
pumping ports & vacuum gauges



Baking at 130°C for 60 h



Set-up of
High Power Test Stand



Step 1 : Target for XFEL (Feb. 2009)

400 μ s, 1.0 MW

1.5 ms, 0.5 MW, 5 Hz

Step 2 : Target for ILC (Mar. 2009)

400 μ s, 2.0 MW, 5 Hz

Step 3 : Target for ILC (May. 2009)

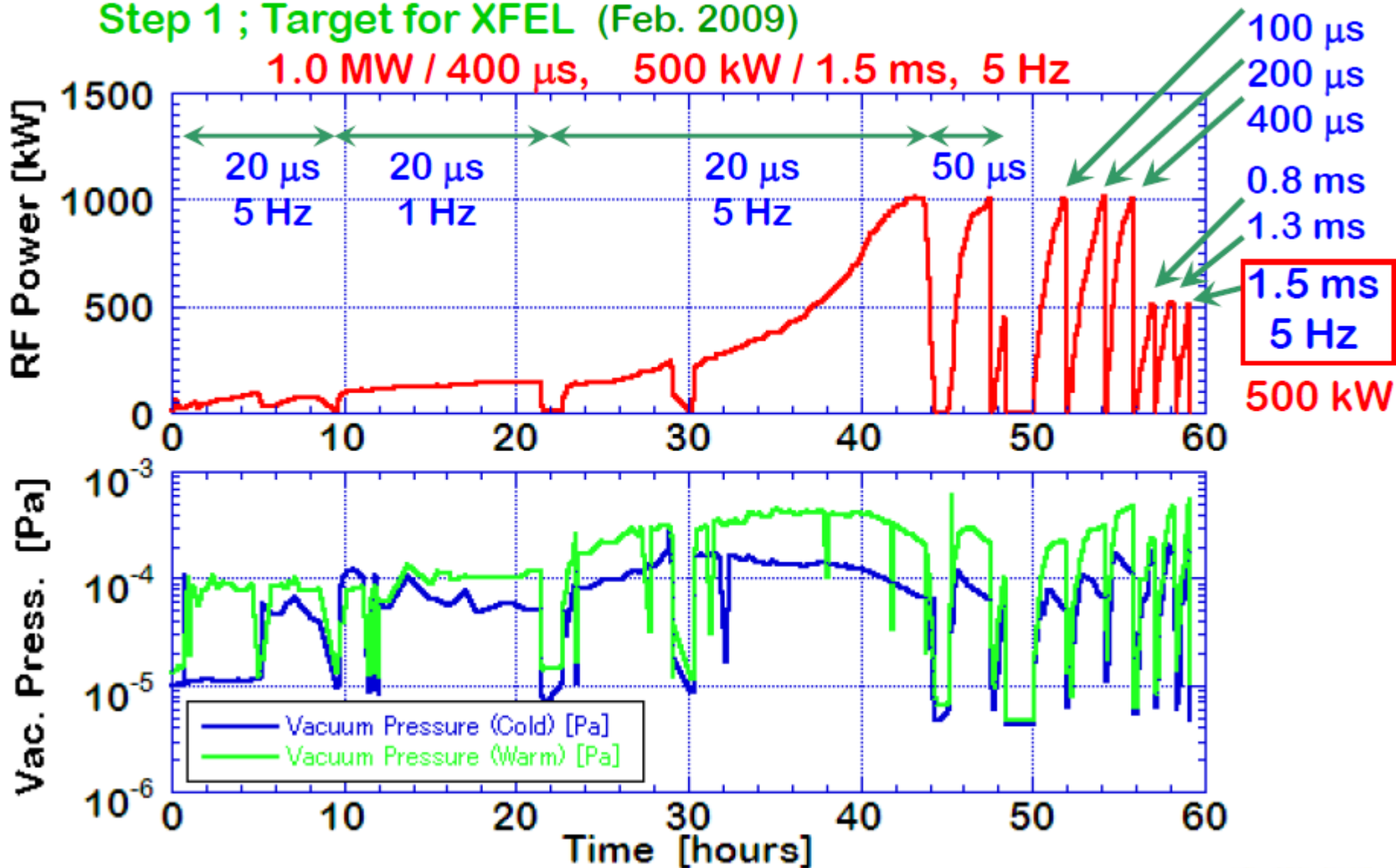
1.5 ms, 1.0 MW, 5 Hz

From E. KAKO presentation SRF 2009

TTF-V RF Conditioning @ KEK (2)

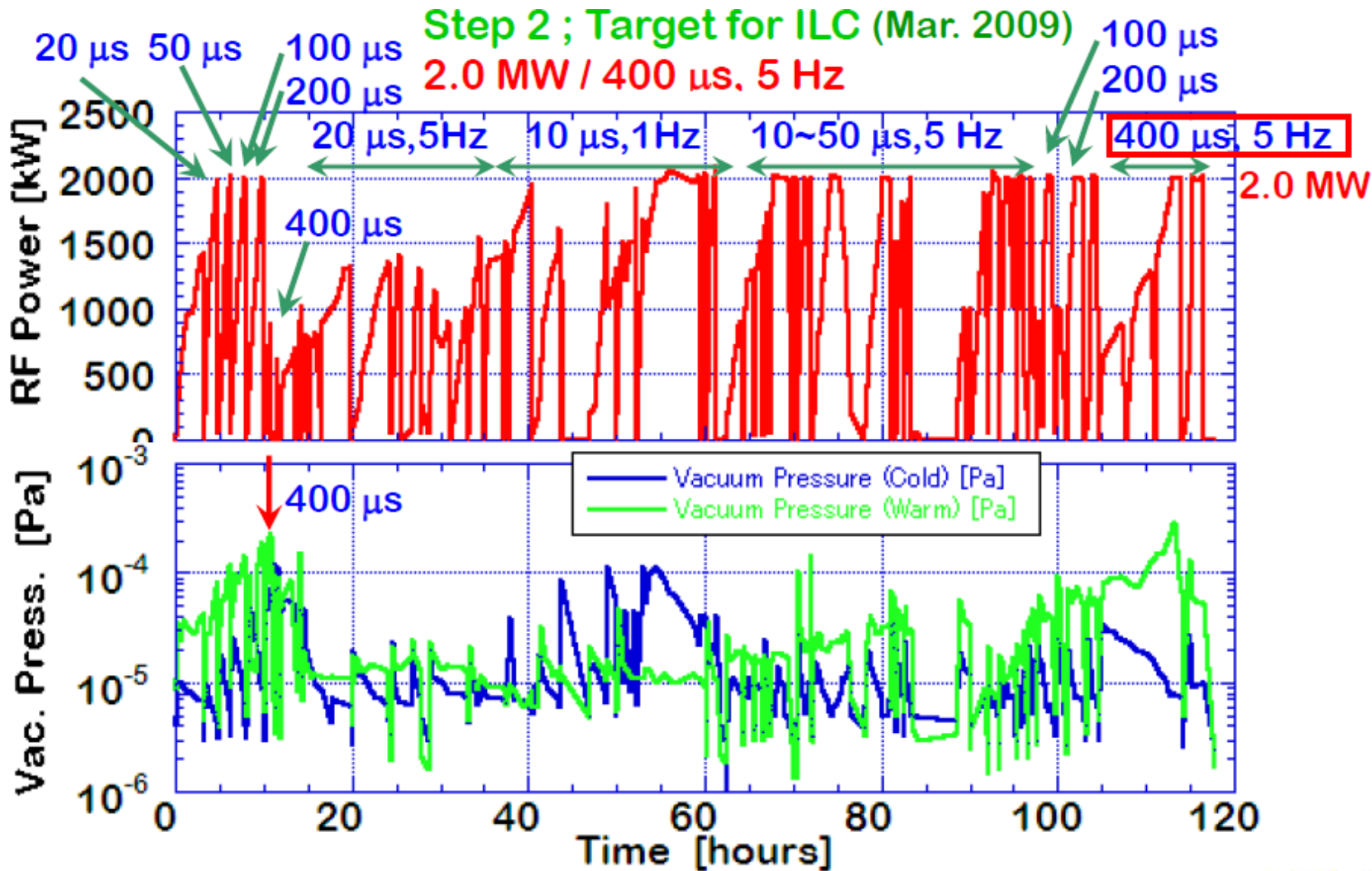
Step 1 ; Target for XFEL (Feb. 2009)

1.0 MW / 400 μ s, 500 kW / 1.5 ms, 5 Hz



From E. KAKO presentation SRF 2009

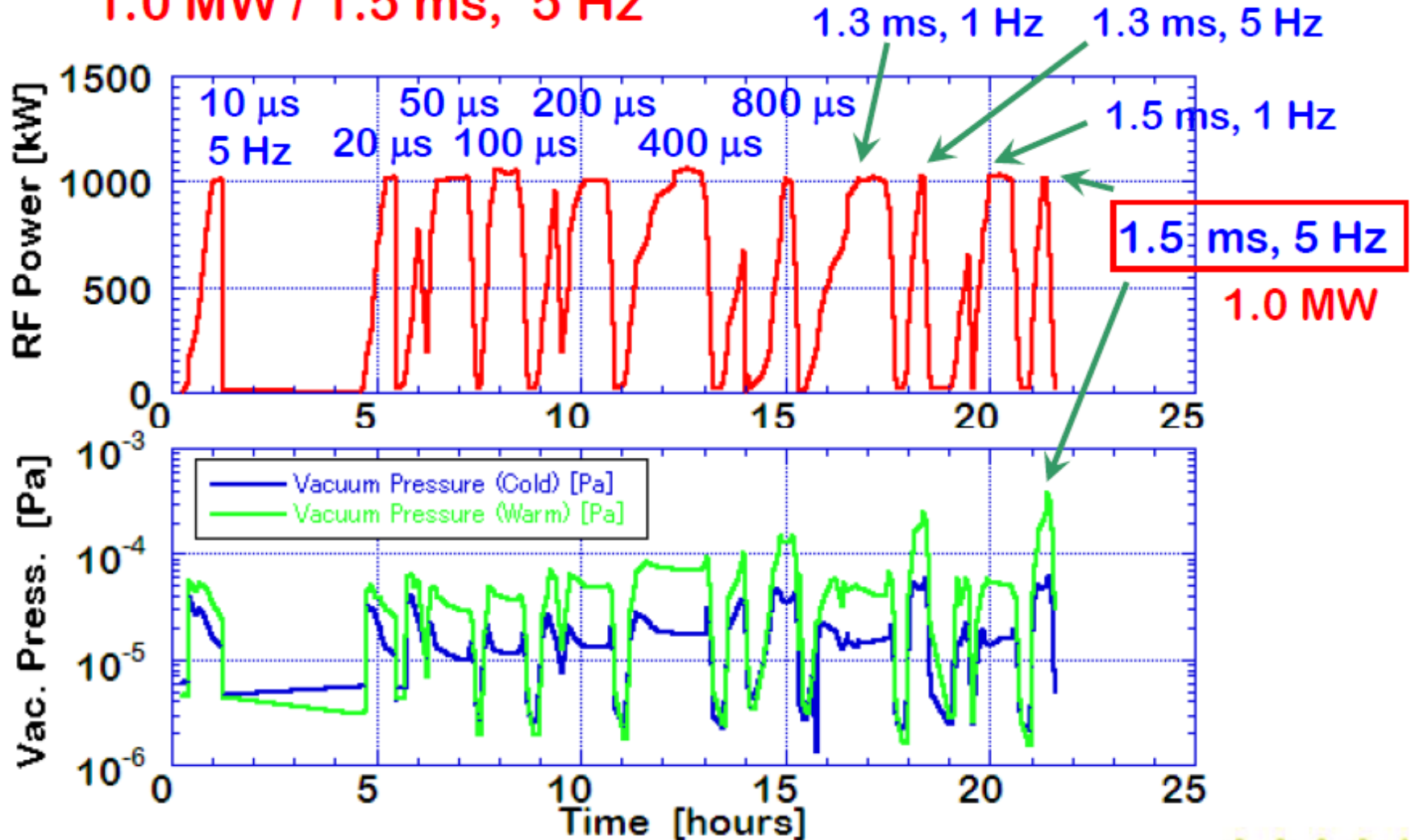
TTF-V RF Conditioning @ KEK (3)



TTF-V RF Conditioning @ KEK (4)

Step 3 ; Target for ILC (May, 2009)

1.0 MW / 1.5 ms, 5 Hz



Summary

- ❑ TTF-V Coupler have been deigned as an alternative Power Coupler for ILC
- ❑ Four TTF-V Couplers and a new Test Box were manufactured
- ❑ The first pair of the TTF-V was successfully RF power test @ LAL following the TTF-III conditioning procedure: Conditioning time was about 24h (Comparable to the XFEL Couplers RF conditioning time)
- ❑ The second pair of the TTF-V was RF Power processed @ KEK following the TTF-III procedure, then, the ILC RF conditioning procedure:



The following RF power levels have been reached:

- 2 MW/ 400 μ s / 5Hz
- 1 MW/ 1500 μ s / 5Hz

- ❑ Perspectives: Further thermal studies are needed for the TTF-V couplers.

Acknowledgment

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Thanks to our DESY colleagues

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